

FEATURES

- High Tg>170°C(DSC);
- Lower insertion loss, Dk/Df@1GHz: 3.9/0.0075;
- Lower Z-axis CTE, offering superior PTH Reliability;
- Excellent Anti-CAF Performance;
- Halogen free and compatible with lead free process.

APPLICATIONS

- Server, Switch, Routers and Base station
- Backplane, Line cards

PRODUCT CONTACTS

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GENERAL PROPERTIES

TEST ITEMS	TREATMENT CONDITION	UNIT	PROPERTY DATA		
			SPEC	TYPICAL VALUE	
Tg	DMA	°C	-	185	
	DSC		-	175	
Flammability	C-48/23/50,E-24/125	Rating	V-0	V-0	
	E-24/125+des				
Volume Resistivity	After moisture resistance	MΩ-cm	≥10 ⁶	3.50×10 ⁷	
	E-24/125		≥10 ³	8.70×10 ⁷	
Surface Resistivity	After moisture resistance	MΩ	≥10 ⁴	1.50×10 ⁷	
	E-24/125		≥10 ³	6.70×10 ⁷	
Dielectric Breakdown	D-48/50+D-0.5/23	KV	≥40	45+KV NB	
Dielectric Constant RC 55%	IPC-TM-650 2.5.5.9(1GHz)	-	≤5.4	3.90	
	IPC-TM-650 2.5.5.13(10GHz)	-		4.05	
Dissipation Factor RC 55%	IPC-TM-650 2.5.5.9(1GHz)	-	≤0.035	0.0075	
	IPC-TM-650 2.5.5.13(10GHz)	-		0.0105	
Thermal Stress	Unetched	288 °C, solder dip	-	>10s No Delamination	
	Etched				
Peel Strength	1OZ	288°C/10s	N/mm	-	1.2
		125°C		-	1.0
Flexural Strength	LW	A	Mpa	≥415	595
	CW			≥345	520
Water Absorption	D-24/23	%	≤0.5	0.12	
CTE Z-axis	Before Tg	TMA	PPM/°C	≤60	36
	After Tg	TMA	PPM/°C	≤300	218
	50-260°C	TMA	%	≤3.5	2.0
Td	10°C/min, N ₂ , 5%Wt Loss	°C	≥325	405	
T288	TMA	min	≥5	60	
T260	TMA	min	≥30	60	